

## IN THE SPECIFICATION

Please replace paragraph [0028] with the following rewritten paragraph [0028]:

[0028] The process provided by the present invention for producing an anisotropically conductive connector is a process comprising:

the first step of providing a frame plate, in which an opening has been formed, forming a layer of a polymeric substance-forming material, which will become an elastic polymeric substance by being cured, in the opening of the frame plate and at a peripheral edge portion thereof and subjecting the polymeric substance-forming material layer to a curing treatment, thereby forming a primary composite body with an insulating sheet base composed of the elastic polymeric substance and formed so as to close the opening in the frame plate supported by an opening edge of the frame plate,

the second step of irradiating the insulating sheet base with a laser beam through a plurality of through-holes for beam transmission in a mask for exposure, in which the through-holes for beam transmission, the diameter of each of which becomes gradually great from one surface toward the other surface of the mask, and each of which extends in a thickness-wise direction of the mask, have been formed in accordance with a pattern corresponding to a pattern of conductive path elements to be formed, from the side of the one surface of the mask for exposure, thereby forming a secondary composite body with an insulating sheet body, in which a plurality of through-holes for forming conductive paths, each extending in a thickness-wise direction of the sheet body, have been formed, and which has been formed so as to close the opening in the frame plate, supported by the opening edge of the frame plate, and

the third step of charging a conductive path element-forming material with conductive particles dispersed in a polymeric substance-forming material, which will become an elastic polymeric substance by being cured, into each of the through-holes for forming conductive

paths in the secondary composite body, thereby forming conductive path element-forming material layers, and subjecting the conductive path element-forming material layers to a curing treatment, thereby forming an anisotropically conductive sheet with conductive path elements integrally provided in the through-holes for forming conductive ~~path elements~~ paths of the insulating sheet body.

Please replace paragraph [0030] with the following rewritten paragraph [0030]:

[0030] In the processes according to the present invention for producing the anisotropically conductive connector, it may be preferable that particles exhibiting magnetism be used as the conductive particles in the conductive path element-forming material, and

a magnetic field be applied to the conductive path element-forming material layers formed in the insulating sheet body in a thickness-wise direction thereof, thereby orienting the conductive particles dispersed in each of the conductive path element-forming material layers in the thickness-wise direction of the conductive path element-forming material layer, and the conductive path element-forming material layers be subjected to the curing treatment in this state, thereby forming the anisotropically conductive sheet with the conductive path elements integrally provided in the through-holes for forming conductive ~~path elements~~ paths of the insulating sheet body.

Please replace paragraph [0031] with the following rewritten paragraph [0031]:

[0031] In the processes according to the present invention for producing the anisotropically conductive connector, it may also be preferable that the polymeric substance-forming material be applied on to one surface of a flat plate-like supporting plate, the frame plate be arranged in such a manner that the other surface of the frame plate is separated from

and opposed to the one surface of the supporting plate, the mask for exposure be arranged in such a manner that one surface of the mask is separated from and opposed to one surface of the frame plate, these be superimposed on one another to pressurize them, thereby forming polymeric substance-forming material layers of the intended form in forming spaces including internal spaces of the openings of the frame plate, spaces between the frame plate and the mask for exposure and internal spaces of the through-holes for beam transmission in the mask for exposure, and the polymeric substance-forming material layers be subjected to the curing treatment, thereby forming a primary composite body, in which a plurality of insulating sheet bases each having projected part-forming portions are arranged so as to close the openings in the frame plate, and peripheral edge portions of the insulating sheet bases are supported by their corresponding opening edges of the frame plate,

the insulating sheet bases be irradiated with the laser beam through the through-holes for beam transmission in the mask for exposure from the other surface side of the mask for exposure, thereby forming a secondary composite body with a plurality of insulating sheet bodies, in which through-holes for forming conductive paths, each extending in a thickness-wise direction of the sheet body, have been formed in the projected part-forming portions, supported by their corresponding opening edges of the frame plate, and

the conductive path element-forming material with the conductive particles dispersed in the polymeric substance-forming material, which will become the elastic polymeric substance by being cured, be charged into the through-holes for forming conductive paths of the respective projected part-forming portions in the secondary composite body, thereby forming conductive path element-forming material layers, and the conductive path element-forming material layers be subjected to the curing treatment, thereby forming anisotropically conductive sheets with conductive path elements each having a one surface-side projected part protruding from the one surface of the insulating sheet body integrally provided in the

through-holes for forming conductive ~~path-elements~~ paths in each of the insulating sheet bodies. In this case, it may be preferable to use, as the supporting plate, one composed of the same material as used in the frame plate.

Please replace paragraph [0035] with the following rewritten paragraph [0035]:

[0035] In the processes according to the present invention for producing the anisotropically conductive sheet, it may further be preferable that particles exhibiting magnetism be used as the conductive particles in the conductive path element-forming material,

a magnetic field be applied to the conductive path element-forming material layers formed in the insulating sheet body in a thickness-wise direction thereof, thereby orienting the conductive particles dispersed in each of the conductive path element-forming material layers in the thickness-wise direction of the conductive path element-forming material layer, and the conductive path element-forming material layers be subjected to the curing treatment in this state, thereby forming the conductive path elements integrally provided in the through-holes for forming conductive ~~path-elements~~ paths of the insulating sheet body.

Please replace the unnumbered subparagraph beginning at page 53, line 24 through page 54, line 1, with the following rewritten subparagraph:

[Fig. 14] is a cross-sectional view illustrating a state that through-holes for forming conductive paths have been formed in the insulating sheet base, and a resin layer for forming projected parts have been formed in ~~a resin layer~~ through-holes for forming projected parts.

Please replace the unnumbered subparagraph at page 57, lines 2-6, with the following rewritten subparagraph:

[Fig. 30] is a cross-sectional view illustrating the construction of a secondary composite body obtained by forming respective through-holes for forming conductive ~~path elements~~ paths in the insulating sheet base of a primary composite body.

Please replace the subparagraphs beginning at page 60, lines 1-18, with the following rewritten subparagraphs:

[Fig. 51] is a cross-sectional view illustrating a state that an insulating sheet base has been irradiated with a laser beam through a plurality of through-holes for beam transmission in a mask for exposure arranged on one surface of the insulating sheet base in a conventional process for producing an anisotropically conductive sheet, thereby forming through-holes for forming conductive ~~path elements~~ paths.

[Fig. 52] is a cross-sectional view illustrating a state that in the case where the thickness of an insulating sheet base used has been great, the insulating sheet base has been irradiated with a laser beam through a plurality of the through-holes for beam transmission in the mask for exposure arranged on one surface of the insulating sheet base in the conventional process for producing an anisotropically conductive sheet, thereby forming through-holes for forming conductive ~~path elements~~ paths.

Please replace paragraph [0062] (beginning at page 71, line 2 through page 72, line 7), with the following rewritten paragraph [0062]:

[0062] As the addition type liquid silicone rubber, is preferably used that having a viscosity of 100 to 1,250 Pa·s, more preferably 150 to 800 Pa·s, particularly preferably 250 to 500 Pa·s at 23°C. If this viscosity is lower than 100 Pa·s, precipitation of the conductive

particles in such addition type liquid silicone rubber is easy to occur in a conductive path element-forming material 11A for obtaining the conductive path elements 11, which will be described subsequently, so that good storage stability is not achieved. In addition, the conductive particles are not oriented so as to align in the thickness-wise direction of a layer 11B of the conductive path element-forming material when a parallel magnetic field is applied to the conductive path element-forming material layer 11B, so that it may be difficult in some cases to form chains of the conductive particles in an even state. If this viscosity exceeds 1,250 Pa·s on the other hand, the viscosity of the resulting conductive path element-forming material 11A for obtaining the conductive path elements 11, which will be described subsequently, becomes too high, so that it may be difficult in some cases to form the conductive path element-forming material layer 11B in each of the through-holes 17 for forming conductive ~~path elements~~ paths in the insulating sheet body 15. In addition, the conductive particles are not sufficiently moved even when a parallel magnetic field is applied to the conductive path element-forming material layer 11B. Therefore, it may be difficult in some cases to orient the conductive particles so as to align in the thickness-wise direction.

Please replace the unnumbered paragraph at page 77, lines 11-20, with the following rewritten paragraph:

The amount of the coupling agent used is suitably selected within limits not affecting the conductivity of the conductive particles P. However, it is preferably such an amount that a coating rate (proportion of an area coated with the coupling agent to the surface area of the conductive ~~core~~ particles) of the coupling agent on the surfaces of the conductive particles P amounts to at least 5%, more preferably 7 to 100%, further preferably 10 to 100%, particularly preferably 20 to 100%.



Please replace the unnumbered paragraph at page 79, lines 10-19, with the following rewritten paragraph:

The through-holes ~~[[21]]~~ 17 for forming conductive paths in the insulating sheet body 15 each has a shape for forming a cylindrical internal space extending perpendicularly to the one and other surfaces of the insulating sheet body 15 and are in a state independent of each other, i.e., a state separated in such a manner that conductive path elements to be formed in the through-holes ~~[[21]]~~ 17 for forming conductive ~~path elements~~ paths secure sufficient insulating property between them.

Please replace paragraph [0104] beginning at page 103, line 18 through page 104, line 7, with the following rewritten paragraph [0104]:

[0104] In addition, the other surface-side projected parts 12B in the conductive path elements 11 are formed by forming projected part-forming portions within the through-holes ~~18B~~ 18A for forming projected parts in the resin layer 18 for forming projected parts and dissolving and removing the resin layer 18 for forming projected parts, whereby the other surface-side projected parts 12B having the expected conductive property can be surely formed on all the conductive path elements 11 without causing the problem that the projected parts may be broken off in some cases according to, for example, the process making use of the mask for printing to form the projected parts when the mask for printing is separated and removed, even when the arrangement pitch of the conductive path elements 11 is extremely small.

Please replace paragraph [0105] beginning at page 104, line 23 through page 105, line 8, with the following rewritten paragraph [0105]:

[0105] Further, since it is only necessary to arrange the mask 20 for exposure upon the formation of the through-holes 17 for forming conductive parts and through-holes 18A for forming projected parts in such a manner that one surface 20A, ~~which is a surface irradiated with the laser beam in the production process,~~ comes into contact with one surface of the insulating sheet base 16, i.e., to conduct a simple process that the mask for exposure is produced, and this mask is then turned upside down in a series of production steps, the expected anisotropically conductive sheet 10 can be produced with high yield and advantage.

Please replace paragraph [0107] with the following rewritten paragraph [0107]:

[0107] Upon the production of, for example, the anisotropically conductive sheet having the construction that the conductive path elements are formed so as to protrude from both surfaces of the insulating sheet body, the one surface-side projected parts and other surface-side projected parts may also be formed by also arranging a second mask for exposure, which has the same construction as a first mask for exposure, on the other surface of the insulating sheet body, on the one surface of which the first mask for exposure has been arranged, in such a manner that the ~~other~~ one surface thereof comes into contact, charging the conductive path element-forming material into the through-holes for forming conductive paths in the insulating sheet body, the through-holes for beam transmission in the first mask for exposure and the through-holes for beam transmission in the second mask for exposure in a state that any one surface of the masks has been closed, thereby forming conductive path element-forming material layers, subjecting the conductive path element-forming material layers to the curing treatment, thereby forming conductive path elements, and removing the first and second masks for exposure.



Please replace the unnumbered paragraph beginning at page 108, line 25, through page 109, line 3 with the following rewritten paragraph:

Each of the anisotropically conductive sheets 10 in this embodiment has the same construction as that shown in Fig. 9 ~~except that it has one conductive path element 11~~, and the conductive path element 11 is formed so as to protrude from one surface of the anisotropically conductive sheet 10.

Please replace the unnumbered paragraph beginning at page 113, lines 14-22, with the following rewritten paragraph:

By forming the spaces for forming anisotropically conductive sheets by arranging the frame plate ~~[[41]]~~ 31 and the two spacers 33, 34 in such a manner, the anisotropically conductive sheets 10 of the intended form can be surely formed, and moreover a great number of anisotropically conductive sheets 10 independent of one another can be surely formed because adjacent anisotropically conductive sheets 10 are prevented from joining with each other.

Please replace paragraph [0115] beginning at page 114, line 24, through page 115, line 8, with the following rewritten paragraph [0115]:

[0115] [Third step]

In this third step, as illustrated in Fig. 24, the above-described conductive path element-forming material 11A is applied on to one surface of the secondary composite body 30B obtained in the second step to charge the conductive path element-forming material 11A into the respective through-holes ~~[[21]]~~ 17 for forming conductive paths in the secondary composite body 30B, thereby forming conductive path element-forming material layers 11B

in the interiors of the respective through-holes 17 for forming conductive paths in the secondary composite body 30B.

Please replace paragraph [0124] beginning at page 125, line 20 through page 126, line 6, with the following rewritten paragraph [0124]:

[0124] [Fourth step]

In this fourth step, the mask 20 for exposure is separated and removed from the one surface of the secondary composite body 30B to expose one end portions of the conductive path elements 11 so as to form the one surface-side projected parts [[12]] 12A. In this state, the whole of the secondary composite body 30B is immersed in a proper solvent S as illustrated in Fig. 33 to dissolve and remove the resin layer 18 for forming projected parts, thereby exposing the other end portions of the conductive path elements 11 so as to form the other surface-side projected parts [[12]] 12B, thus obtaining the anisotropically conductive connector 30 of the construction shown in Fig. 26.

Please replace paragraph [0127] with the following rewritten paragraph [0127]:

[0127] Upon the production of, for example, an anisotropically conductive connector equipped with the anisotropically conductive sheets having the construction that the conductive path elements are formed so as to protrude from both surfaces of the insulating sheet body, the anisotropically conductive connector may further be so produced that a resin film of, for example, the same material as that forming the resin layer for forming projected parts is interposed and arranged between the upper surface-side spacer and the mask for exposure, these are superimposed on one another to pressurize them, thereby forming polymeric substance-forming material layers of the intended form in spaces for forming anisotropically conductive sheets, including internal spaces of the openings of the

frame plate and internal spaces of the respective openings of the lower surface-side spacer and upper surface-side spacer, the polymeric substance-forming material layers are subjected to the curing treatment and irradiated with the laser beam through the through-holes for beam transmission from the other surface side of the mask for exposure, thereby forming through-holes for forming projected parts in the resin film and the resin layer for forming projected parts and at the same time forming through-holes for forming conductive path elements in each of the insulating sheet bases, conductive path element-forming material layers are formed within the spaces for forming conductive ~~path-elements~~ paths in a state that the mask for exposure has been removed or remained arranged, the conductive path element-forming material layers are subjected to the curing treatment, thereby forming conductive path elements, and the resin film and the resin layer for forming projected parts are dissolved and removed to form the one surface-side projected parts and the other surface-side projected parts.

Please replace the unnumbered paragraph beginning at page 145, line 21, through page 146, line 3, with the following rewritten paragraph:

Each of the through-holes for forming conductive paths in the insulating sheet body at ~~one surface thereof~~ was in a form of a substantially truncated pyramid that the diameter becomes gradually small from one surface toward the other surface, the size of an opening diameter  $a$  in the one surface was maximum, and an opening diameter ratio  $a/b$  of the size of the opening diameter  $a$  in the one surface to the size an opening diameter  $b$  in the other surface was 1.2.

Please replace the unnumbered paragraph at page 150, lines 3-24, with the following rewritten paragraph:

The above-described mask for exposure was arranged in such a manner that the one surface thereof comes into contact with one surface of the insulating sheet base in the ~~composite body~~ laminate, and the insulating sheet base was irradiated with a laser beam under the following conditions through a plurality of the through-holes for beam transmission from the other surface side of the mask for exposure by means of the laser beam machine “Impact L-500” (manufactured by Sumitomo Heavy Industries, Ltd.), thereby forming a plurality of through-holes for forming conductive paths, each extending through in a thickness-wise direction of the insulating sheet base, in the insulating sheet base, and at the same time forming a plurality of through-holes for forming projected parts, each extending continuously with its corresponding through-hole for forming a conductive path in the thickness-wise direction, in the resin layer for forming projected parts, thus forming a primary composite body with the resin layer for forming projected parts provided on the other surface of an insulating sheet body.

Please replace paragraph [0158] at page 155, lines 15-26, with the following rewritten paragraph [0158]:

[0158] <Comparative Example 1>

A comparative anisotropically conductive sheet was produced in the same manner as in Example 1 except that the mask for exposure was arranged in such a manner that the other surface thereof comes into contact with the one surface of the insulating sheet base in Example 1, and the insulating sheet base was irradiated with the laser beam through a plurality of the through-holes for beam transmission in the mask for exposure from the one

surface side of the mask for exposure, thereby forming through-holes for forming conductive ~~path elements~~ paths.

Please replace paragraph [0159] beginning at page 156, line 25 through page 157, line 26, with the following rewritten paragraph [0159]:

[0159] <Comparative Example 2>

A comparative anisotropically conductive sheet was produced in the same manner as in Example 3 except that the mask for exposure was arranged in such a manner that the other surface thereof comes into contact with the one surface of the insulating sheet base in Example 3, the insulating sheet base was irradiated with the laser beam through a plurality of the through-holes for beam transmission in the mask for exposure from the one surface side of the mask for exposure, thereby forming through-holes for forming conductive ~~path elements~~ paths in the insulating sheet base to form an insulating sheet body, masks for printing, in which openings had been formed in accordance with a pattern of conductive path elements to be formed, were arranged on both surfaces of the insulating sheet body to form conductive path element-forming material layers within spaces for forming conductive path elements, including internal spaces of the openings in the masks for printing and internal spaces of the through-holes for forming conductive paths in the insulating sheet base, the conductive path element-forming material layers were subjected to the curing treatment, thereby forming conductive path elements integrally provided in the insulating sheet body, and the masks for printing were separated and removed, thereby forming one surface-side projected parts and the other surface-side projected parts.

Please replace paragraph [0168] with the following rewritten paragraph [0168]:

[0168] [Formation of secondary composite body]

The primary composite body obtained in the above-described manner was arranged on a working stage of a CO<sub>2</sub> laser beam machine “Impact L-500” (manufactured by Sumitomo Heavy Industries, Ltd.), and the insulating sheet bases provided in the respective openings of the frame plate were irradiated with a laser beam ~~under the following conditions~~ from the other surface side of the mask for exposure in the primary composite body, thereby forming a plurality of through-holes for forming conductive ~~path elements~~ paths in each of the insulating sheet bases. Thereafter, the back surface supporting plate was separated, thereby obtaining a secondary composite body.

Please replace paragraph [0169] at page 168, lines 4-25, with the following rewritten paragraph [0169]:

[0169] [Formation of anisotropically conductive sheet]

The secondary composite body obtained in the above-described manner was arranged on a printing stage through a rubber sheet for sealing within a chamber of a vacuum printing machine, the above-described mask for printing was further arranged in alignment on the secondary composite body, and the pressure within the chamber of the vacuum printing machine was then reduced to  $1 \times 10^{-4}$  atm. In this state, the conductive path element-forming material was applied by screen printing, and the pressure of the atmosphere within the chamber was raised to an atmospheric pressure, thereby charging the conductive path element-forming material into internal spaces of the through-holes for forming conductive ~~path elements~~ paths and internal spaces of the through-holes for beam transmission in the mask for exposure. Thereafter, the mask for printing was removed, and the conductive ~~paste~~



path element-forming material excessively remaining on the mask for exposure was removed by means of a squeegee, thereby forming conductive path element-forming material layers.

Please replace paragraph [0170] with the following rewritten paragraph [0170]:

[0170] The anisotropically conductive sheets in the thus-obtained anisotropically conductive connector will be described specifically. Each of the anisotropically conductive sheets has dimensions of 6,000  $\mu\text{m}$  in a lateral direction and 1,400  $\mu\text{m}$  in a vertical direction. In each of the anisotropically conductive sheets, fifty conductive path elements corresponding to the electrodes to be inspected in Wafer W1 for evaluation are arranged at a pitch of 100  $\mu\text{m}$  in a line. Each of the conductive path elements is in a columnar form of a rectangle in section that the thickness is 118  $\mu\text{m}$ , and the dimensions are 60  $\mu\text{m}$  in the lateral direction and 200  $\mu\text{m}$  in the vertical direction. The thickness of the insulating sheet body portion mutually insulating the conductive path elements is 100  $\mu\text{m}$ . A ratio ( $T2/T1$ ) of the thickness  $T2$  of the insulating sheet body ~~portion~~ element to the thickness  $T1$  of each of the conductive path ~~elements~~ portion is 1.18. The thickness (thickness of one of the forked portions) of a portion supported by the frame plate in each of the anisotropically conductive sheets is 20  $\mu\text{m}$ .

Please replace the unnumbered paragraph beginning at page 171, line 18, through page 172, line 12, with the following rewritten paragraph:

The anisotropically conductive sheets in the thus-obtained Anisotropically Conductive Connectors (B1) to (B10) will be described specifically. Each of the anisotropically conductive sheets has dimensions of 6,000  $\mu\text{m}$  in a lateral direction and 1,200  $\mu\text{m}$  in a vertical direction. In each of the anisotropically conductive sheets, fifty conductive path elements corresponding to the electrodes to be inspected in Wafer W1 for evaluation are arranged at a

pitch of 100  $\mu\text{m}$  in a line. Each of the conductive path elements has a sectional form that the thickness is 118  $\mu\text{m}$ , and the dimensions are within a range of about 70 to 80  $\mu\text{m}$  in the lateral direction and within a range of 210 to 220  $\mu\text{m}$  in the vertical direction. The thickness of the insulating sheet body portion mutually insulating the conductive path elements is 100  $\mu\text{m}$ . A ratio ( $T2/T1$ ) of the thickness  $T2$  of the insulating sheet body ~~portion~~ element to the thickness  $T1$  of each of the conductive path ~~elements~~ portion is 1.18. The thickness (thickness of one of the forked portions) of a portion supported by the frame plate in each of the anisotropically conductive sheets is 20  $\mu\text{m}$ .

Please replace the unnumbered paragraph beginning at page 175, line 16, through page 176, line 13, with the following rewritten paragraph:

In this state, a heat treatment was conducted at a temperature of 100°C for 90 minutes, thereby curing the polymeric substance-forming material layers to form insulating sheet bases in the respective openings of the frame plate. The laminate was arranged on a working stage of a CO<sub>2</sub> laser beam machine “Impact L-500” (manufactured by Sumitomo Heavy Industries, Ltd.) in a state that the upper side pressurizing plate, lower side pressurizing plate and releasing film had been removed, and the insulating sheet bases provided in the respective openings of the frame plate were irradiated with a laser beam ~~under the following conditions~~ from the other surface side of the mask for exposure, thereby forming a plurality of through-holes for forming conductive ~~path-elements~~ paths, each extending through in the thickness-wise direction, in each of the insulating sheet bases, and at the same time forming through-holes for forming projected parts, each extending continuously with its corresponding through-hole for forming a conductive path in the thickness-wise direction, in the resin layer for forming projected parts. Thereafter, the supporting plate was separated, thereby obtaining a primary composite body.

Please replace paragraph [0176] beginning at page 176, line 14, through page 177, line 13, with the following rewritten paragraph [0176]:

[0176] [Formation of secondary composite body]

The primary composite body obtained in the above-described manner was arranged on a printing stage through a rubber sheet for sealing composed of fluorine-containing rubber within a chamber of a vacuum printing machine, the above-described mask for printing was further arranged in alignment on the primary composite body, and the pressure within the chamber of the vacuum printing machine was then reduced to  $1 \times 10^{-4}$  atm. In this state, the conductive path element-forming material was applied by screen printing, and the pressure of the atmosphere within the chamber was raised to an atmospheric pressure, thereby charging the conductive path element-forming material into spaces for forming conductive path elements, including internal spaces of the through-holes for beam transmission in the mask for exposure, internal spaces of the through-holes for forming conductive ~~path elements~~ paths and internal spaces of the through-holes for forming projected parts in the resin layer for forming projected parts. Thereafter, the mask for printing was removed, and the conductive path element-forming material excessively remaining on the mask for exposure was removed by means of a squeegee, thereby forming conductive path element-forming material layers.

Please replace the unnumbered paragraph at page 179, lines 5-20, with the following rewritten paragraph:

In each of the anisotropically conductive sheets, fifty conductive path elements corresponding to the electrodes to be inspected in Wafer W1 for evaluation are arranged at a pitch of  $100 \mu\text{m}$  in a line. Each of the conductive path elements is in a columnar form of a rectangle in section that the thickness is  $143 \mu\text{m}$ , and the dimensions are  $60 \mu\text{m}$  in the lateral

direction and 200  $\mu\text{m}$  in the vertical direction. The thickness of the insulating sheet body portion mutually insulating the conductive path elements is 100  $\mu\text{m}$ . A ratio ( $T2/T1$ ) of the thickness  $T2$  of the insulating sheet body ~~portion~~ element to the thickness  $T1$  of each of the conductive path ~~elements~~ portion is 1.43. The thickness (thickness of one of the forked portions) of a portion supported by the frame plate in each of the anisotropically conductive sheets is 20  $\mu\text{m}$ .

Please replace the unnumbered paragraph beginning at page 181, line 24, through page 182, line 22, with the following rewritten paragraph:

The anisotropically conductive sheets in the thus-obtained Anisotropically Conductive Connectors (D1) to (D10) will be described specifically. Each of the anisotropically conductive sheets has dimensions of 6,000  $\mu\text{m}$  in a lateral direction and 1,200  $\mu\text{m}$  in a vertical direction. In each of the anisotropically conductive sheets, fifty conductive path elements corresponding to the electrodes to be inspected in Wafer W1 for evaluation are arranged at a pitch of 100  $\mu\text{m}$  in a line. In each of the anisotropically conductive sheets, a thickness at a portion where the conductive path element was formed is within a range of 133 to 143  $\mu\text{m}$ , and each of the conductive path elements has a sectional form that the dimensions thereof are within a range of about 70 to 80  $\mu\text{m}$  in the lateral direction and within a range of 210 to 220  $\mu\text{m}$  in the vertical direction in the interior of the insulating sheet body. The thickness of the insulating sheet body portion mutually insulating the conductive path elements is 100  $\mu\text{m}$ . A ratio ( $T2/T1$ ) of the thickness  $T2$  of the insulating sheet body ~~portion~~ element to the thickness  $T1$  of each of the conductive path ~~elements~~ portion is 1.18. The thickness (thickness of one of the forked portions) of a portion supported by the frame plate in each of the anisotropically conductive sheets is 20  $\mu\text{m}$ .

Please replace the unnumbered paragraph beginning at page 183, line 18, through page 184, line 14, with the following rewritten paragraph:

Namely, Wafer W1 for evaluation was arranged on a test table, and an anisotropically conductive connector to be evaluated was arranged in alignment on this Wafer W1 for evaluation in such a manner that the conductive parts for connection composed of conductive path elements thereof are located on the respective electrodes to be inspected of Wafer W1 for evaluation. Circuit Board T for inspection was then arranged in alignment on this anisotropically conductive connector in such a manner that the inspection electrodes thereof are located on the respective conductive parts for connection of the anisotropically conductive connector. Circuit Board T for inspection was then pressurized downward under a load of 58.95 kg (load applied to every conductive part for connection: 3 g on the average). An electric resistance between each of the 19,650 inspection electrodes in Circuit Board T for evaluation and the lead electrode of Wafer W1 for evaluation was successively measured at room temperature (25°C) as an electric resistance (hereinafter referred to as “conduction resistance”) in the conductive part for connection to calculate out a proportion of conductive parts for connection that the conduction resistance was lower than 1  $\Omega$ .